



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T183-4000-18

Maximum allowable mean on-state current				I _{TAV}		4000 A		
Repetitive peak off-state voltage				V _{DRM}		1000...1800 V		
Repetitive peak reverse voltage				V _{RRM}				
Turn-off time				t _q		320 μs		
V _{DRM} , V _{RRM} , V	1000	1100	1200	1300	1400	1500	1600	1800
Voltage code	10	11	12	13	14	15	16	18
T _j , °C	-60...+125							

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	4000 3840 4750	$T_c=82\text{ }^{\circ}\text{C}$, Double side cooled $T_c=85\text{ }^{\circ}\text{C}$, Double side cooled $T_c=70\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	6280	$T_c=82\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	70.0 81.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			74.0 85.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor	$A^2s\cdot 10^3$	24500 32800	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			22700 29900	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000...1800	$T_{j\text{ min}} < T_j < T_{j\text{ max}}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100...1900	$T_{j\text{ min}} < T_j < T_{j\text{ max}}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	$T_j=T_{j\text{ max}}$; Gate open	

TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	$T_j = T_{j\max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	5	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	630	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	$^{\circ}$ C	-60...+50	
T_j	Operating junction temperature	$^{\circ}$ C	-60...+125	
MECHANICAL				
F	Mounting force	kN	60.0...70.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

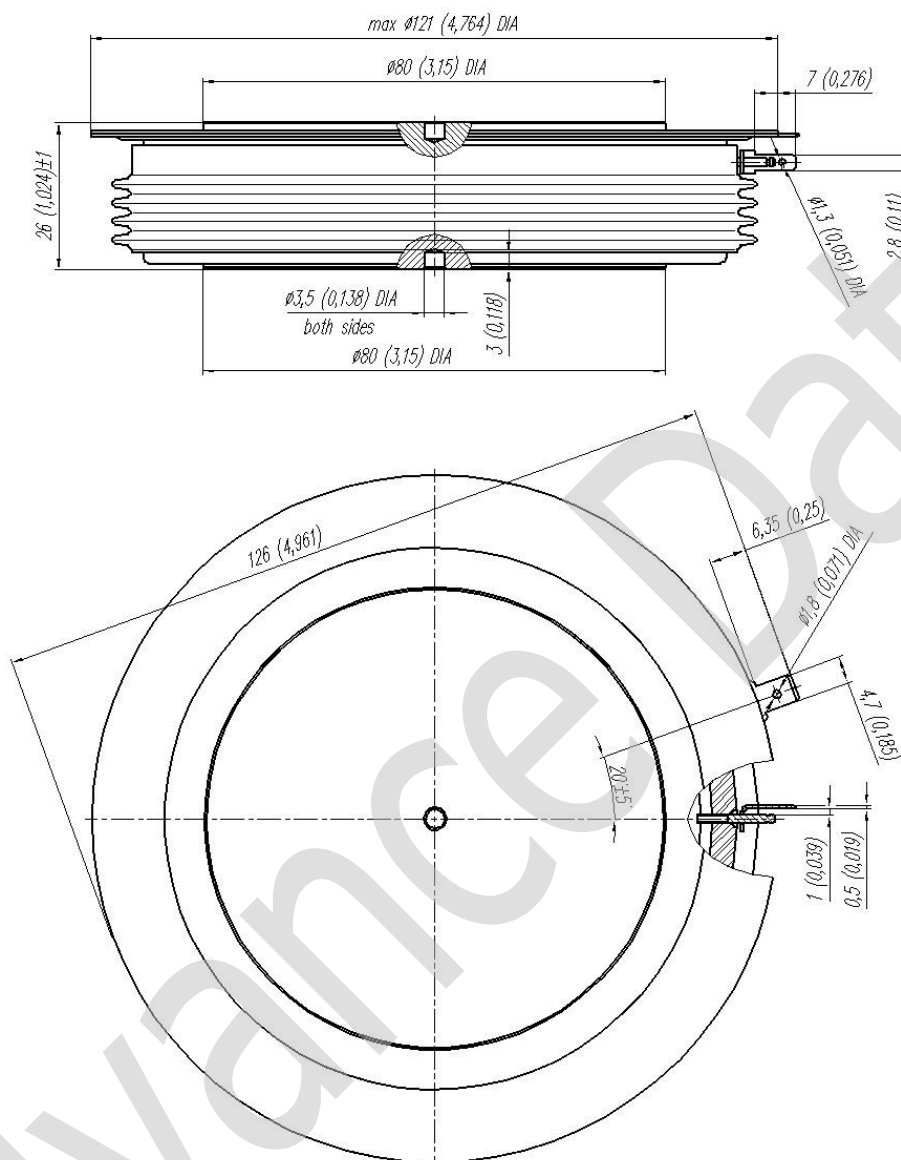
Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	1.35	$T_j=25\text{ }^{\circ}\text{C}$; $I_{TM}=6300\text{ A}$	
$V_{T(TO)}$	On-state threshold voltage, max	V	0.85	$T_j=T_{j\text{ max}}$	
r_T	On-state slope resistance, max	m Ω	0.080	$0.5\pi I_{TAV} < I_T < 1.5\pi I_{TAV}$	
I_L	Latching current, max	mA	1500	$T_j=25\text{ }^{\circ}\text{C}$; $V_D=12\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$	
I_H	Holding current, max	mA	300	$T_j=25\text{ }^{\circ}\text{C}$; $V_D=12\text{ V}$; Gate open	
BLOCKING					
I_{DRM} , I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	$T_j=T_{j\text{ max}}$; $V_D=V_{DRM}$; $V_R=V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μs	500, 1000, 1600	$T_j=T_{j\text{ max}}$; $V_D=0.67\cdot V_{DRM}$; Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	$T_j= T_{j\text{ min}}$ $T_j=25\text{ }^{\circ}\text{C}$ $T_j= T_{j\text{ max}}$	$V_D=12\text{ V}$; $I_D=3\text{ A}$; Direct gate current
I_{GT}	Gate trigger direct current, max	mA	500 300 200	$T_j= T_{j\text{ min}}$ $T_j= 25\text{ }^{\circ}\text{C}$ $T_j= T_{j\text{ max}}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j=T_{j\text{ max}}$; $V_D=0.67\cdot V_{DRM}$;	
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
SWITCHING					
t_{gd}	Delay time, max	μs	4.00	$T_j=25\text{ }^{\circ}\text{C}$; $V_D=1000\text{ V}$; $I_{TM}=I_{TAV}$; $di/dt=200\text{ A}/\mu\text{s}$; Gate pulse: $I_G=2\text{ A}$; $V_G=20\text{ V}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt=2\text{ A}/\mu\text{s}$	
t_q	Turn-off time ²⁾ , max	μs	320	$dv_D/dt=50\text{ V}/\mu\text{s}$; $T_j=T_{j\text{ max}}$; $I_{TM}= I_{TAV}$; $di_R/dt=-10\text{ A}/\mu\text{s}$; $V_R=100\text{V}$; $V_D=0.67\cdot V_{DRM}$	
Q_{rr}	Recovered charge, max	μC	3200	$T_j=T_{j\text{ max}}$; $I_{TM}=1000\text{ A}$;	
t_{rr}	Reverse recovery time, max	μs	34	$di_R/dt=-10\text{ A}/\mu\text{s}$;	
I_{rr}	Reverse recovery current, max	A	188	$V_R=100\text{ V}$	

THERMAL					
R _{thjc}	Thermal resistance, junction to case, max	°C/W	0.0065	Direct current	Double side cooled
R _{thjc-A}			0.0143		Anode side cooled
R _{thjc-K}			0.0117		Cathode side cooled
R _{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0015	Direct current	
MECHANICAL					
m	Weight, max	g	1370		
D _s	Surface creepage distance	mm (inch)	36.50 (1.437)		
D _a	Air strike distance	mm (inch)	16.50 (0.650)		

PART NUMBERING GUIDE							NOTES								
T	183	4000	18	A2	K2	N	1) Critical rate of rise of off-state voltage <table><tr><td>Symbol of Group</td><td>E2</td><td>A2</td><td>T1</td></tr><tr><td>(dv_D/dt)_{crit}, V/μs</td><td>500</td><td>1000</td><td>1600</td></tr></table>	Symbol of Group	E2	A2	T1	(dv _D /dt) _{crit} , V/μs	500	1000	1600
Symbol of Group	E2	A2	T1												
(dv _D /dt) _{crit} , V/μs	500	1000	1600												
1	2	3	4	5	6	7	2) Turn-off time (dv _D /dt=50 V/μs) <table><tr><td>Symbol of Group</td><td>K2</td></tr><tr><td>t_q, μs</td><td>320</td></tr></table>	Symbol of Group	K2	t _q , μs	320				
Symbol of Group	K2														
t _q , μs	320														
1. Phase Control Thyristor															
2. Design version															
3. Mean on-state current, A															
4. Voltage code															
5. Critical rate of rise of off-state voltage, V/μs															
6. Turn-off time (dv _D /dt=50 V/μs)															
7. Ambient conditions: N – normal; T – tropical															

OVERALL DIMENSIONS

Package type: T.H1



All dimensions in millimeters (inches)

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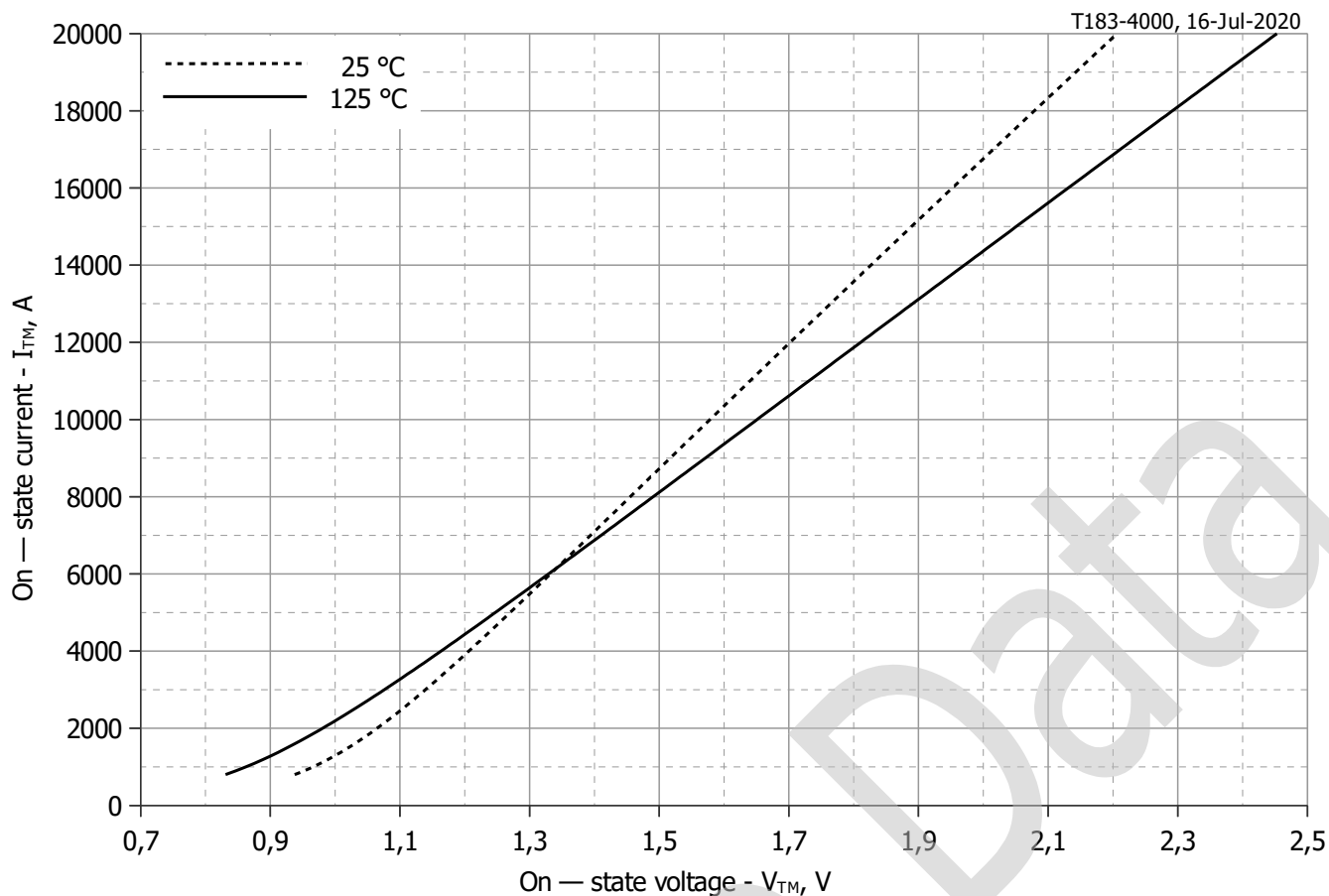


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j\text{ max}}$
A	0.00020047	0.00014317
B	0.00008131	0.00009212
C	0.16075151	0.13494670
D	-0.00715596	-0.00513337

On-state characteristic model (see Fig. 1)

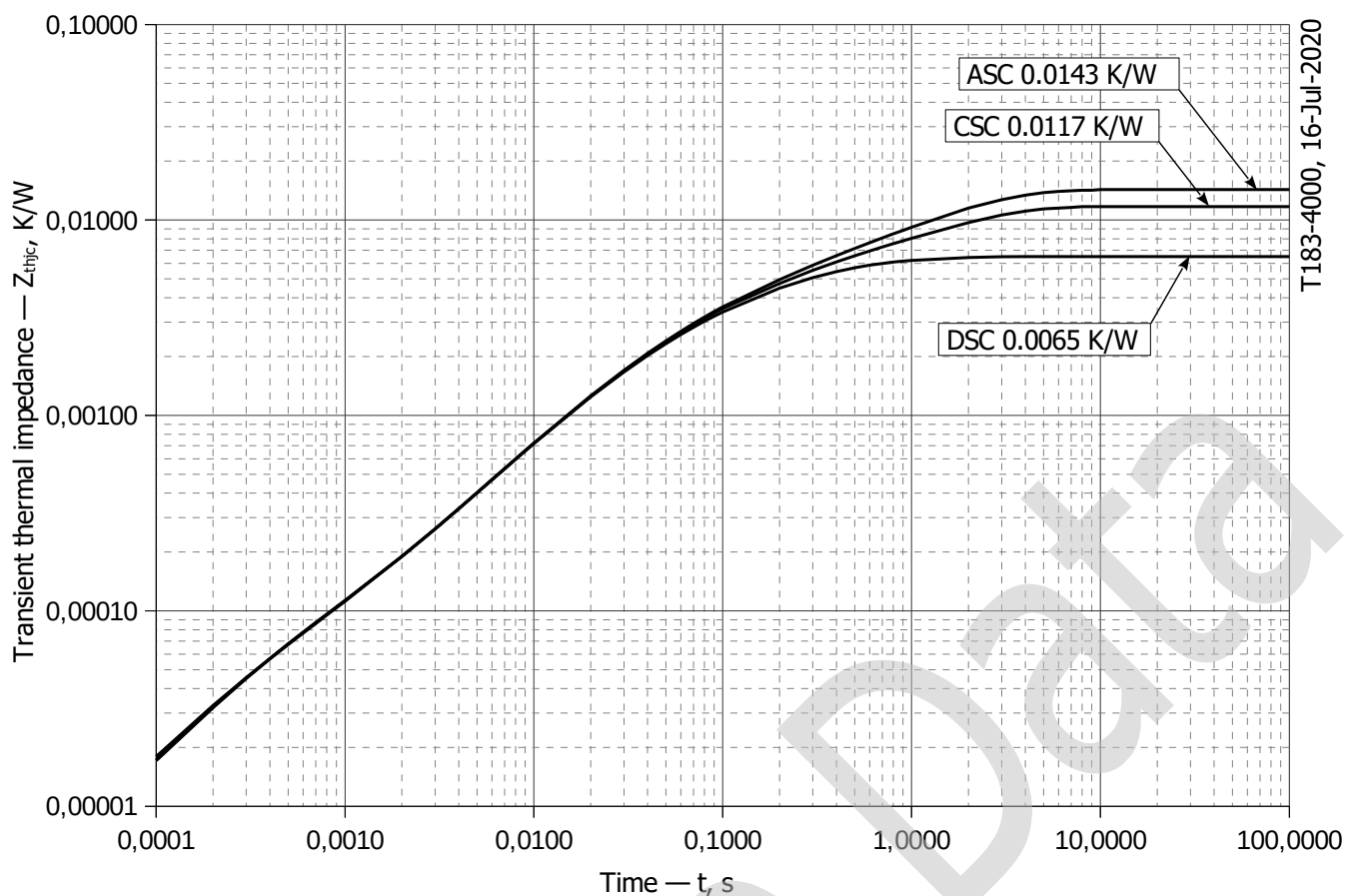


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.001031	0.003117	0.001895	0.0004176	2.061e-005	1.999e-005
τ_i , s	0.7345	0.209	0.05291	0.01652	0.0006764	0.0002168

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.00848	0.001792	0.002597	0.00179	0.0003904	3.851e-005
τ_i , s	1.845	0.9581	0.2011	0.05234	0.01605	0.0003606

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.001475	0.005797	0.002722	0.001822	0.0003923	3.824e-005
τ_i , s	0.8755	1.835	0.1997	0.05221	0.01594	0.0003499

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

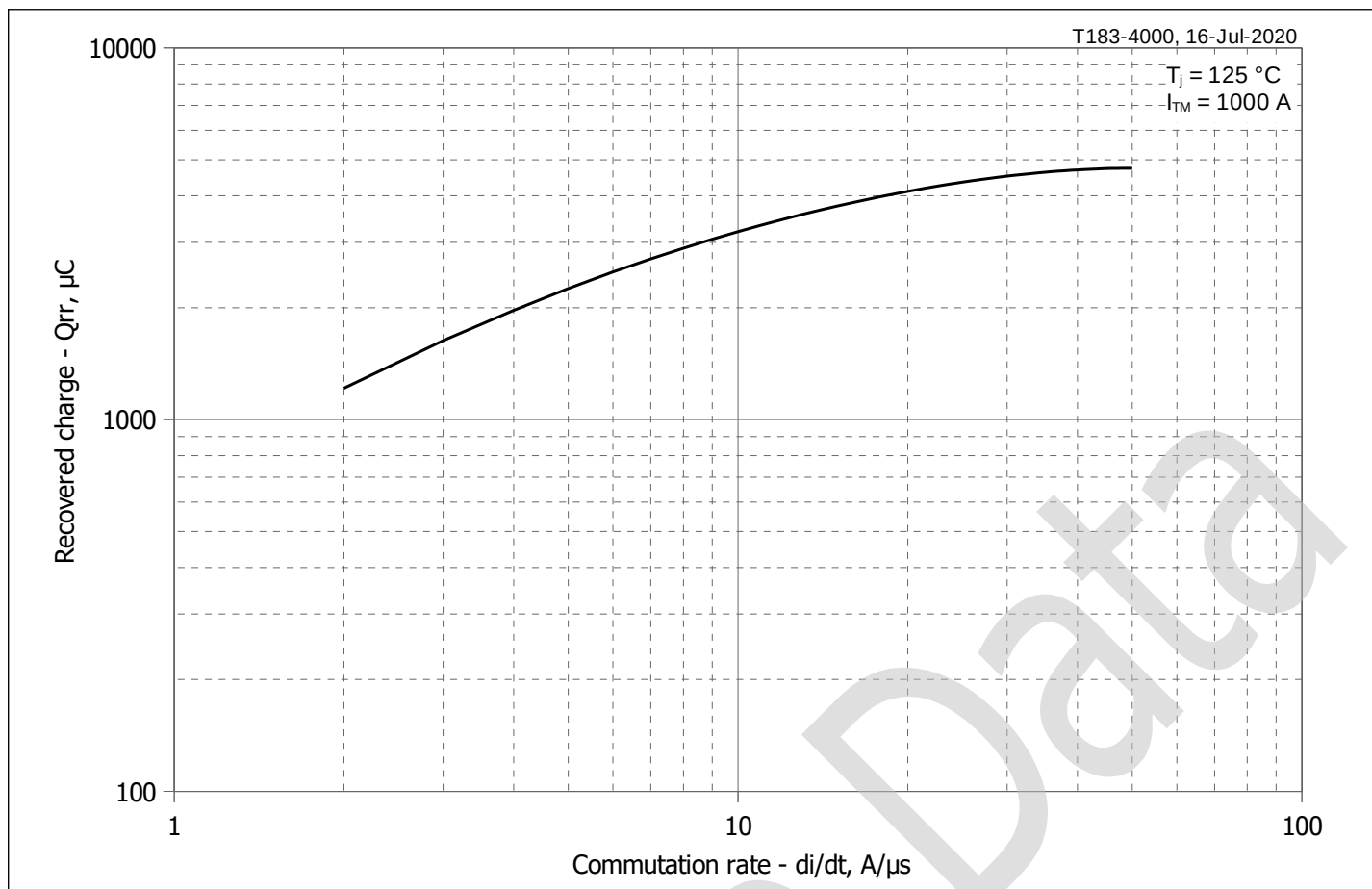


Fig. 3 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)

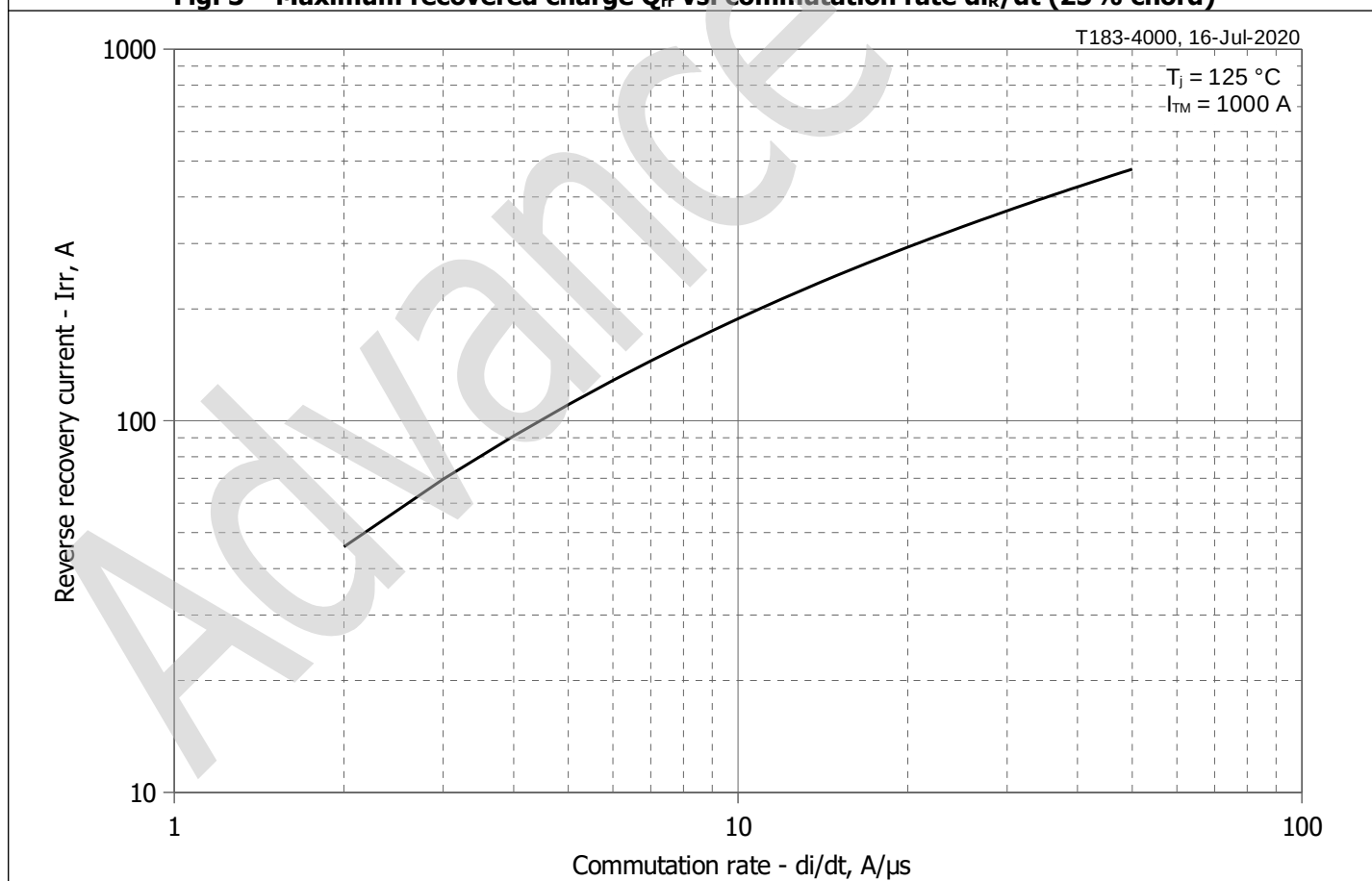


Fig. 4 – Maximum reverse recovery current I_{rr} vs. commutation rate di_R/dt



Fig. 5 – Maximum recovery time t_{rr} vs. commutation rate di_R/dt (25% chord)

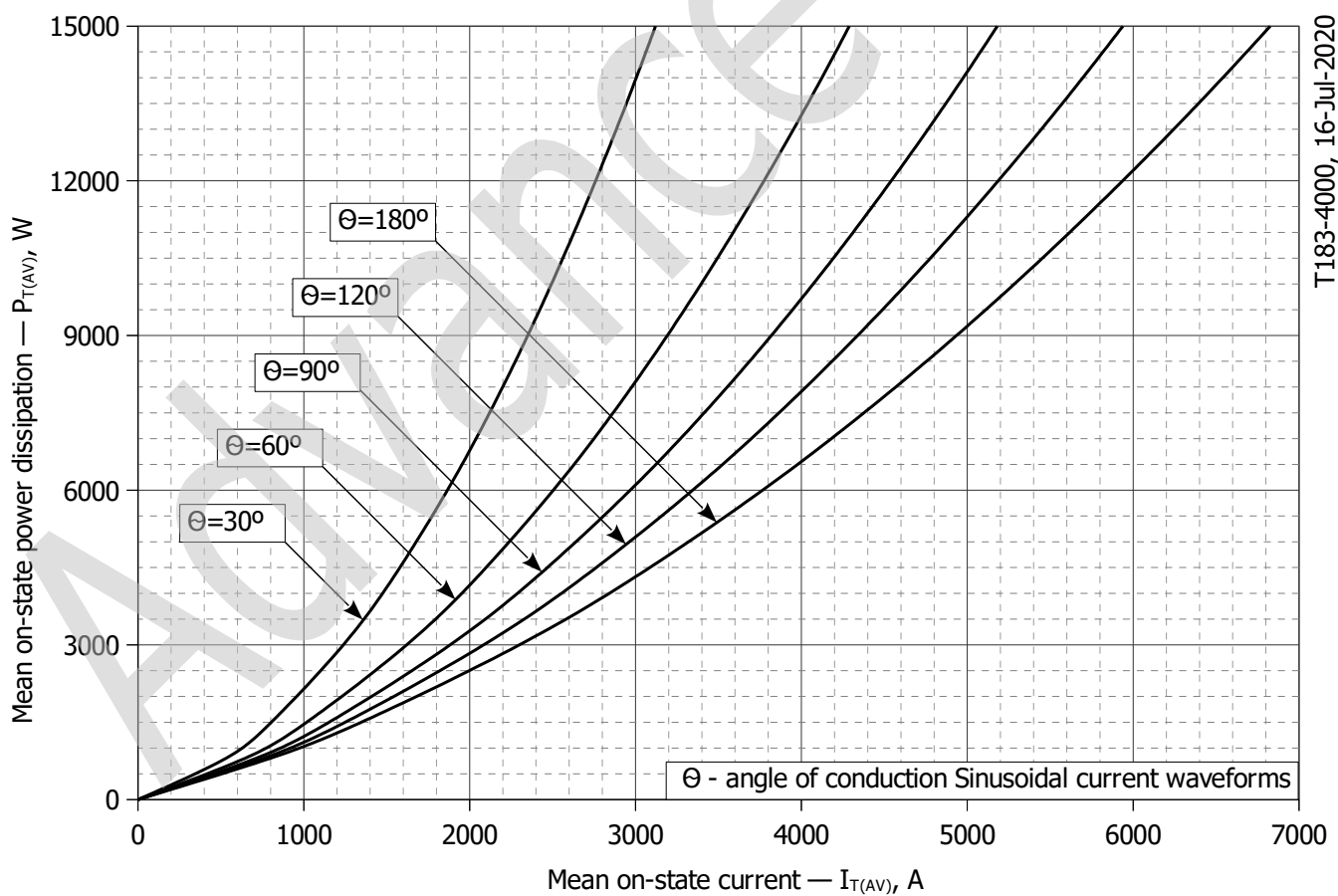


Fig. 6 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$, DSC)

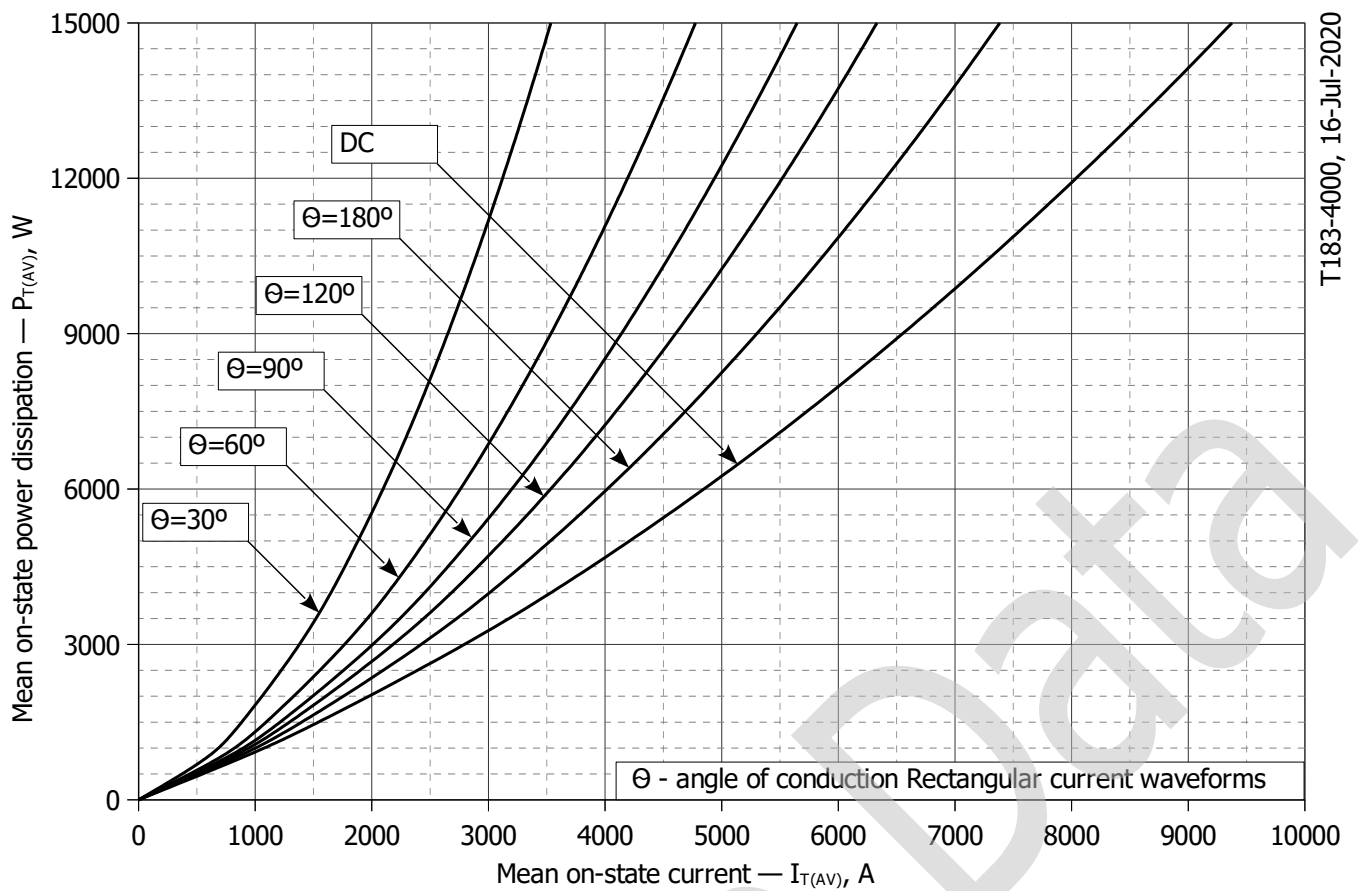


Fig. 7 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC (f=50Hz, DSC)

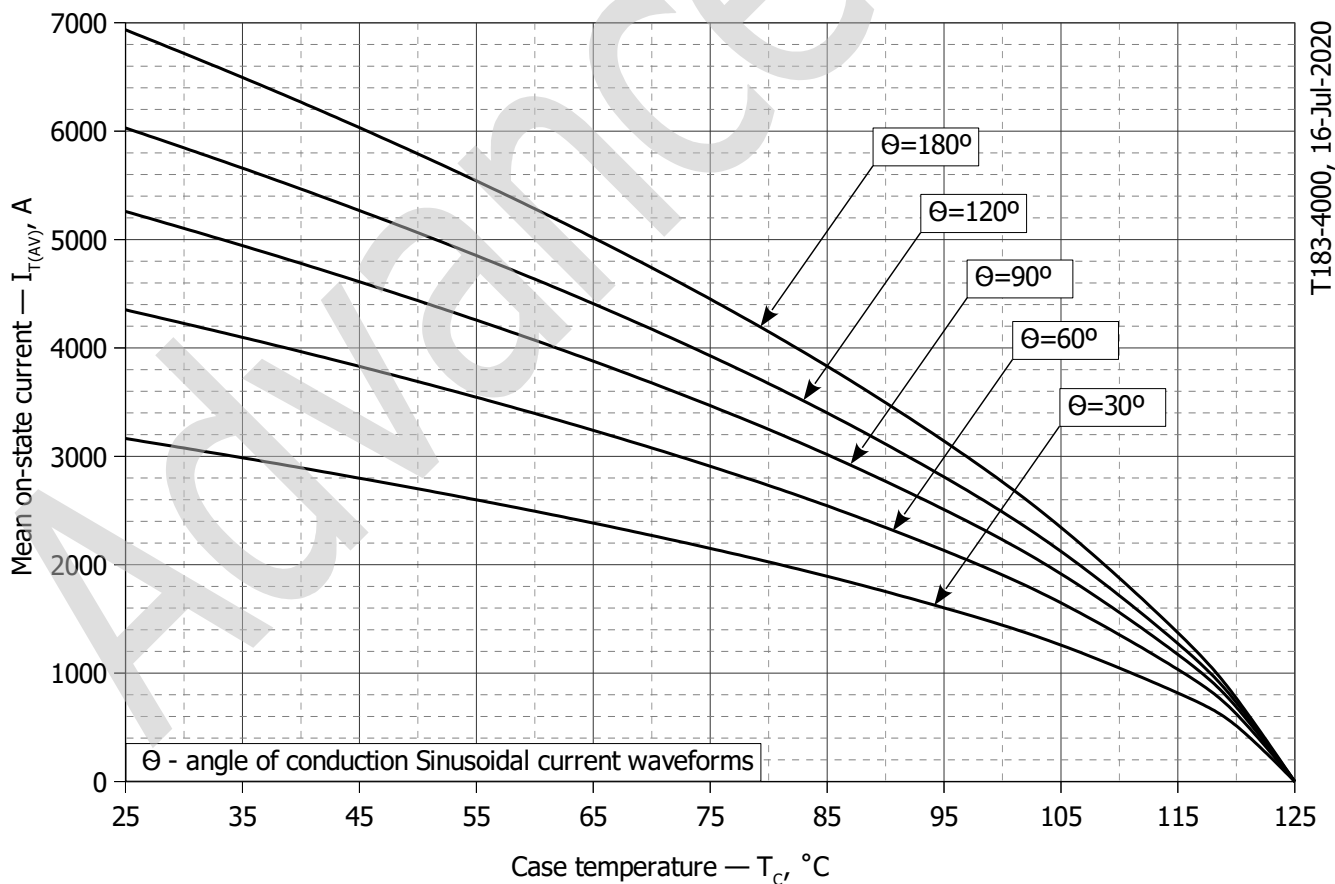


Fig. 8 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles (f=50Hz, DSC)

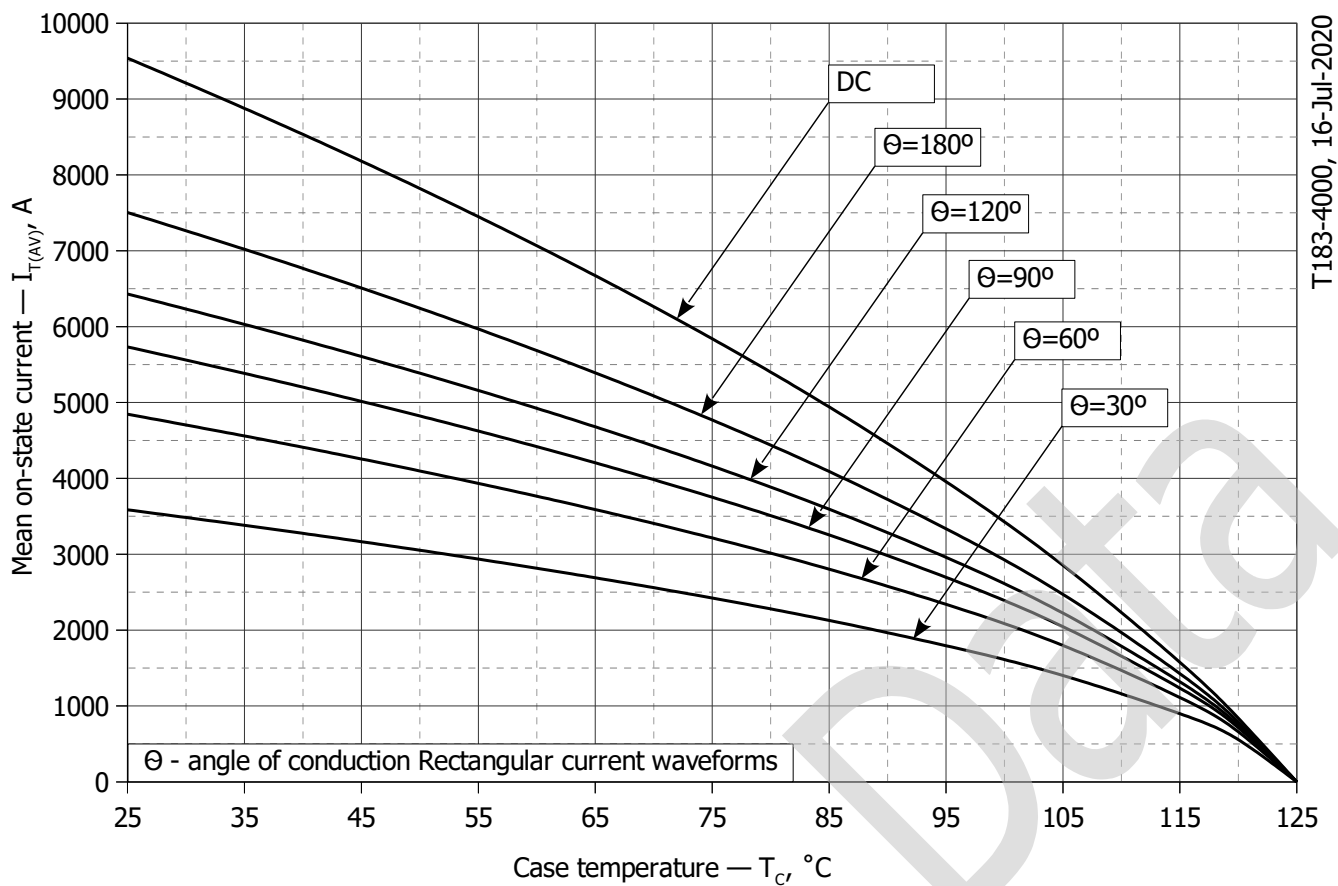


Fig. 9 - Mean on-state current I_{TAV} vs. case temperature T_C for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$, DSC)

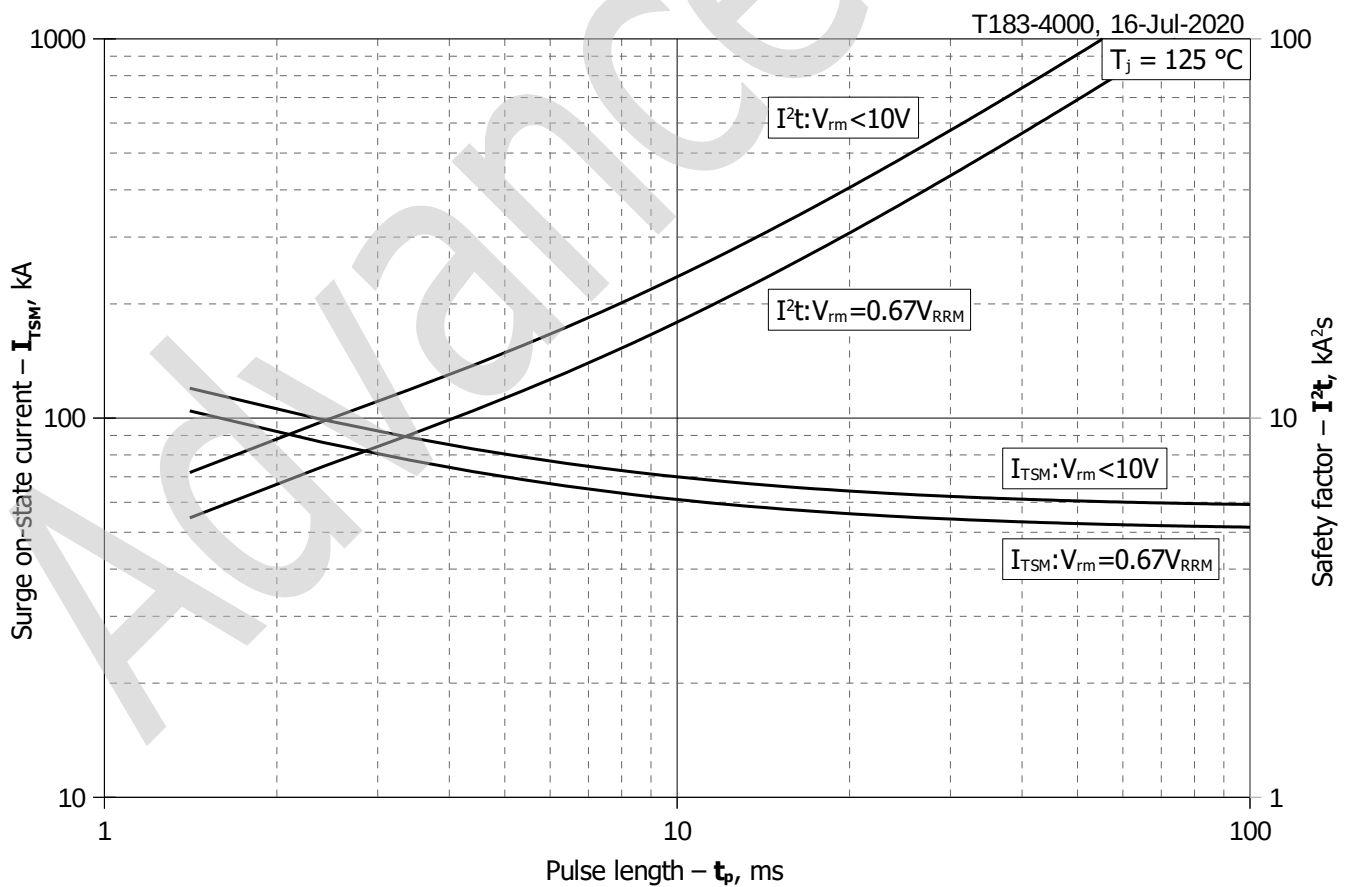


Fig. 10 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

